CLAIMS

1-7. (Canceled)

8. (Currently Amended) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern interposed between a pair of magnetic insulation layers so as to be in contact with the pair of magnetic insulation layers ~~and~~ so that the magnetic insulation layers contact one another in the area not in contact with the conductive pattern and so as to have no specific gap between the at least one fine, continuous conductive pattern and th pair of magnetic insulation layers, the at least one fine, continuous conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5, wherein each of the at least one continuous conductive pattern is continuous on one surface of one of the magnetic insulation layers, and each of the at least one continuous conductive pattern is substantially free of discontinuities.

9. (Original) A lamination ceramic chip inductor, according to claim 8, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

10. (Withdrawn) A lamination ceramic chip inductor, according to claim 9, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

11. (Canceled)

12. (Currently Amended) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern interposed between a pair of magnetic insulation layers so as to be in contact with the pair of magnetic insulation layers ~~and~~ so that the magnetic insulation layers contact one another in the area not in contact with the conductive pattern and so as to have no specific gap between the at least one fine, continuous conductive pattern and th pair of magnetic insulation layers, the at least one fine, continuous conductive pattern formed by an electroforming process using a photoresist, the at least one conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5, wherein each of the at least one continuous conductive pattern is continuous on one surface of one of the magnetic insulation layers, and each of the at least one continuous conductive pattern is substantially free of discontinuities.

13. (Original) A lamination ceramic chip inductor, according to claim 12, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

14. (Withdrawn) A lamination ceramic chip inductor, according to claim 13, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

15-20. (Canceled)

21. (Withdrawn) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern formed between at least one pair of insulation layers so as to have no specific gap between the at least one conductive pattern and

the at least one pair of insulation layers, the at least one conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

22. (Withdrawn) A lamination ceramic chip inductor, according to claim 21, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

23. (Withdrawn) A lamination ceramic chip inductor, according to claim 22, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

24. (Withdrawn) A lamination ceramic chip inductor, according to claim 21, wherein the at least one pair of insulation layers are magnetic.

25. (Withdrawn) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern formed by an electroforming process using a photoresist, the at least one conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5,

wherein the at least one conductive pattern is formed between at least one pair of insulation layers so as to have no specific gap therebetween.

26. (Withdrawn) A lamination ceramic chip inductor, according to claim 25, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

27. (Withdrawn) A lamination ceramic chip inductor, according to claim 26, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

28. (Withdrawn) A lamination ceramic chip inductor, according to claim 25, wherein the at least one pair of insulation layers are magnetic.

29. (Withdrawn) A lamination ceramic chip inductor, comprising at least one conductive pattern formed between at least one pair of insulation layers so as to have no specific gap between the at least one conductive pattern and the at least one pair of insulation layers, the at least one conductive pattern consisting of metal selected from the group consisting of Ag, Au, Pt, Pd, Cu, Ni and alloys thereof.

30. (Withdrawn) A lamination ceramic chip inductor, according to claim 29, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

31. (Withdrawn) A lamination ceramic chip inductor, according to claim 30, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

32. (Withdrawn) A lamination ceramic chip inductor, according to claim 29, wherein the at least one pair of insulation layers are magnetic.

33. (Withdrawn) A lamination ceramic chip inductor according to claim 29, wherein the lamination ceramic chip inductor has a high impedance at a low resistance while comprising a small number of layers.

34. (Withdrawn) A lamination ceramic chip inductor, comprising at least one conductive pattern formed by an electroforming process using a photoresist, wherein the at least one conductive pattern is formed between at least one pair of insulation layers so as to have no specific gap therebetween, the at least one conductive pattern consisting of metal selected from the group consisting of Ag, Au, Pt, Pd, Cu, Ni and alloys thereof.

35. (Withdrawn) A lamination ceramic chip inductor, according to claim 34, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

36. (Withdrawn) A lamination ceramic chip inductor, according to claim 35, wherein the plurality of conductive patterns include an electroformed conductive pattern having a shape of a straight line.

37. (Withdrawn) A lamination ceramic chip inductor, according to claim 34, wherein the at least one pair of insulation layers are magnetic.

38. (Withdrawn) A lamination ceramic chip inductor, according to claim 34, wherein the lamination ceramic chip inductor has a high impedance at a low resistance while comprising a small number of layers.

39. (Withdrawn) A lamination ceramic chip inductor, according to claim 8, wherein the conductive pattern has edges which are not blurred.

40. (Withdrawn) A lamination ceramic chip inductor, according to claim 11, wherein the at least one pair of magnetic insulation layers are sintered, and the

conductive pattern is surrounded by the sintered magnetic layers with a high density and no specific gap between the conductive pattern and the magnetic layers.

41. (Withdrawn) A lamination ceramic chip inductor, according to claim 12, wherein the conductive pattern has edges which are not blurred.

42. (Withdrawn) A lamination ceramic chip inductor, according to claim 15, wherein the at least one pair of magnetic insulation layers are sintered, and the conductive pattern is surrounded by the sintered magnetic layers with a high density and no specific gap between the conductive pattern and the magnetic layers.

43. (Withdrawn) A lamination ceramic chip inductor, according to claim 21, wherein the conductive pattern has edges which are not blurred.

44. (Withdrawn) A lamination ceramic chip inductor, according to claim 24, wherein the at least one pair of magnetic insulation layers are sintered, and the conductive pattern is surrounded by the sintered magnetic layers with a high density as a result of the no specific gap between the conductive pattern and the magnetic layers.

45. (Withdrawn) A lamination ceramic chip inductor, according to claim 25, wherein the conductive pattern has edges which are not blurred.

46. (Withdrawn) A lamination ceramic chip inductor, according to claim 28, wherein the at least one pair of magnetic insulation layers are sintered, and the conductive pattern is surrounded by the sintered magnetic layers with a high density as a result of the no specific gap between the conductive pattern and the magnetic layers.

47. (Withdrawn) A lamination ceramic chip inductor, according to claim 29, wherein the conductive pattern has edges which are not blurred.

48. (Withdrawn) A lamination ceramic chip inductor, according to claim 32, wherein the at least one pair of magnetic insulation layers are sintered, and the conductive pattern is surrounded by the sintered magnetic layers with a high density as a result of the no specific gap between the conductive pattern and the magnetic layers.

49. (Withdrawn) A lamination ceramic chip inductor, according to claim 34, wherein the conductive pattern has edges which are not blurred.

50. (Withdrawn) A lamination ceramic chip inductor, according to claim 37, wherein the at least one pair of magnetic insulation layers are sintered, and the conductive pattern is surrounded by the sintered magnetic layers with a high density as a result of the no specific gap between the conductive pattern and the magnetic layers.

51. (Currently amended) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern, the at least one fine, continuous conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5, further comprising at least one pair of magnetic insulation layers having the at least one conductive pattern formed therebetween, wherein at least one of the pair of magnetic insulation layers contacts the conductive pattern so as to have no specific gap between the at least one fine, continuous conductive pattern and the at least one pair of magnetic insulation layers, wherein each of the at least one continuous conductive pattern is continuous on one surface of one of the magnetic insulation layers of one of the at least one pari of magnetic

insulation layers, and each of the at least one continuous conductive pattern is substantially free of discontinuities.

52. (Previously presented) A lamination ceramic chip inductor, according to claim 51, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

53. (Withdrawn) A greensheet consisting essentially of a plurality of ceramic chip inductors,

each ceramic chip inductor comprising at least one fine, continuous conductive pattern, the at least one fine, continuous conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5,

wherein the plurality of ceramic chip inductors are laminated together to form the greensheet.

54. (Withdrawn) A greensheet, according to claim 53, wherein a plurality of conductive patterns are included, and at least two of the conductive patterns are electrically connected to each other by a thick film conductor formed by printing.

55. (Withdrawn) A greensheet, according to claim 53, further comprising at least one pair of insulation layers having at least one of the plurality of conductive patterns formed therebetween, wherein the at least one pair of insulation layers are magnetic.